

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/550753	US-PGPUB; USPAT	OR	ON	2007/04/30 10:22
S2	2211	(118/724).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/09 17:10
S4	1	("6992022").PN.	USPAT	OR	OFF	2007/04/09 17:13
S5	105	("3783822" "3836751" "3862397" "3916822" "4047496" "4081313" "4101759" "4113547" "4493977" "4497683" "4511788" "4533820" "4540876" "4545327" "4550245" "4649261" "4680451" "4755654" "4789771" "4796562" "4798165" "4821674" "4823735" "4828224" "4836138" "4851358" "4857689" "4920918" "4924807" "4951601" "4978567" "4986838" "4989540" "5034199" "5044943" "5053247" "5074017" "5077875" "5085887" "5098198" "5104276" "5106200" "5108792" "5169684" "5226056" "5252807" "5370739" "5387557" "5436172" "5444217" "5446825").PN. OR ("5683518"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/11 18:53
S6	31448	(RTA or RTP or rapid adj(temperature or thermal) adj3 (processing or anneal\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/11 18:55
S7	12977	(substrate or wafer or holder) with (lift\$4 or mov\$4 or elevat\$3) with heat\$3	US-PGPUB; USPAT	OR	ON	2007/04/11 18:55
S8	5769	(anneal\$4 near3 (gas or vapor))	US-PGPUB; USPAT	OR	ON	2007/04/11 18:56
S9	50830	(first adj2 chamber) and (second adj2 chamber)	US-PGPUB; USPAT	OR	ON	2007/04/11 18:56
S10	286808	control adj2 unit	US-PGPUB; USPAT	OR	ON	2007/04/11 18:57
S11	10337	(atomic adj layer adj (deposit\$3 or epitax\$6)) or ALD	US-PGPUB; USPAT	OR	ON	2007/04/11 18:57

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S12	925	S6 and S7	US-PGPUB; USPAT	OR	ON	2007/04/11 18:57
S13	130	S12 and S8	US-PGPUB; USPAT	OR	ON	2007/04/11 18:57
S14	17	S13 and S9	US-PGPUB; USPAT	OR	ON	2007/04/11 18:58
S16	36	epitaxial.as.	US-PGPUB; USPAT	OR	ON	2007/04/12 07:36
S18	5	("6140256" "6203969" "6419803" "6709523" "6829559").PN. OR ("7060939"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 09:09
S19	3	("4571486" "4649261" "5872889").PN. OR ("7041939"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 09:20
S20	6	("5820366" "5900177" "6183137" "6375348" "6461036" "6610968").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 10:34
S24	63	"5830277"	US-PGPUB; USPAT	OR	ON	2007/04/12 11:08
S25	40	("4058430" "4183780" "4433951" "4435445" "4488506" "4522674" "4525376" "4624736" "4625678" "4640221" "4657617" "4659401" "4668337" "4687544" "4716852" "4726963" "4772485").PN. OR ("5261961").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 12:27
S26	31490	(RTA or RTP or rapid adj(temperature or thermal) adj3 (processing or anneal\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/12 16:27
S27	12985	(substrate or wafer or holder) with (lift\$4 or mov\$4 or elevat\$3) with heat\$3	US-PGPUB; USPAT	OR	ON	2007/04/12 16:28
S28	5775	(anneal\$4 near3 (gas or vapor))	US-PGPUB; USPAT	OR	ON	2007/04/12 15:23
S29	927	S26 and S27	US-PGPUB; USPAT	OR	ON	2007/04/12 15:23
S30	130	S29 and S28	US-PGPUB; USPAT	OR	ON	2007/04/12 15:23
S31	920	(RTA or RTP or rapid adj(temperature or thermal) adj3 (processing or anneal\$4))	EPO; JPO	OR	ON	2007/04/12 16:45
S32	2515	(substrate or wafer or holder) with (lift\$4 or mov\$4 or elevat\$3) with heat\$3	EPO; JPO	OR	ON	2007/04/12 16:29
S33	4	S31 and S32	EPO; JPO	OR	ON	2007/04/12 16:29

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S34	1339262	communication or data	EPO; JPO	OR	ON	2007/04/12 16:45
S35	662	S31 not S34	EPO; JPO	OR	ON	2007/04/13 07:40
S36	1	JP-08288283-\$.did.	EPO; JPO	OR	ON	2007/04/13 07:46
S37	1	JP-08288283-\$.did.	DERWENT	OR	ON	2007/04/13 07:48
S38	255050	takeshi.in.	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 08:09
S39	7938	hino.in.	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 07:56
S40	147244	ricoh.as.	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 07:56
S41	300	S38 and S39	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 07:56
S42	66	S40 and S41	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 07:56
S43	467880	hiroshi.in.	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 08:09
S44	37273	miura.in.	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 08:09
S45	121	S43 and S44 and S40	US-PGPUB; USPAT; JPO	OR	ON	2007/04/13 08:09
S46	2	"6500742"	US-PGPUB; USPAT	OR	ON	2007/04/13 08:34
S47	1	"20020153579"	US-PGPUB; USPAT	OR	ON	2007/04/13 08:48
S48	1	"20030031793"	US-PGPUB; USPAT	OR	ON	2007/04/13 08:56
S49	2	gb-2181458-\$.did.	EPO; DERWENT; IBM_TDB	OR	ON	2007/04/13 08:59
S59	1057442	h01l021/\$.ipc.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 11:55
S60	77375	c23c016/\$.ipc.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 11:56

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S61	92487	c23c014/\$.ipc.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 11:56
S62	1017	(118/729,725or156/345.51,345.52, 345.53,345.54,345.55).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2007/04/19 07:31
S64	224	S62 and gas and heat\$4 and lift\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 15:25
S65	20	"6444027" or "6331212" or "6322631"	USPAT	OR	ON	2007/04/17 15:24
S68	1164422	S59 or S60 or S61	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 15:25
S69	5700	S68 and gas and heat\$4 and lift\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/17 15:27
S70	235	S68 and gas and heat\$4 and lift\$4	EPO; JPO	OR	ON	2007/04/17 16:13
S71	50	applied-materials.as.	US-PGPUB; USPAT	OR	ON	2007/04/18 08:08
S72	90	preheat\$4 same (flash adj heat\$4)	US-PGPUB; USPAT; EPO	OR	ON	2007/04/19 07:16
S73	58793	((moving or lift\$4) with (substrate or wafer))	US-PGPUB; USPAT	OR	ON	2007/04/19 07:16
S74	31	S72 and S73	US-PGPUB; USPAT	OR	ON	2007/04/19 07:30
S75	240	((top or upper) adj3 (gas or vapor) adj inlet) and ((lower or bottom) adj3 (gas or vapor) adj inlet)	US-PGPUB; USPAT	OR	ON	2007/04/19 07:32
S77	374	((top or upper) adj3 (gas or vapor) adj inlet) and ((lower or bottom) adj3 (gas or vapor) adj inlet)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/19 07:32

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S78	55	S77 and (substrate or wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/19 07:40
S80	13	S73 and S78	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/19 08:09
S85	61	"6306216"	US-PGPUB; USPAT	OR	ON	2007/04/19 09:19
S10 0	1544	(heater or (heating adj unit)) with chuck	US-PGPUB; USPAT	OR	ON	2007/04/30 16:28
S10 1	185	(heater or (heating adj unit)) with (connect\$4 or adjacent or next) with chuck	US-PGPUB; USPAT	OR	ON	2007/04/30 14:56
S10 2	182	(RTA or RTP or rapid (temperature or thermal) (processing or anneal\$4)) and S101	US-PGPUB; USPAT	OR	ON	2007/04/30 15:03
S10 3	116	S102 and deposit\$4	US-PGPUB; USPAT	OR	ON	2007/04/30 15:42
S10 4	58	S103 not plasma	US-PGPUB; USPAT	OR	ON	2007/04/30 15:42
S10 5	342	(heater or (heating adj unit)) and chuck and abrasion	US-PGPUB; USPAT	OR	ON	2007/04/30 16:30
S10 6	140	S105 and (wafer or substrate) and deposition	US-PGPUB; USPAT	OR	ON	2007/04/30 16:31